



1763
#5/A
4/5/01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:
Li, et al.
Serial No.: 09/469,709
Filed: December 21, 1999
For: High Through-Put Copper
CMP With Reduced Erosion
And Dishing

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Group Art Unit: 1763

Examiner: G. GOUDREAU

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on March 23, 2001 with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.	
3/23/01 Date	<i>Kevin R. Zerk</i> Signature

RESPONSE TO RESTRICTION REQUIREMENT

In response to the Office Action dated February 23, 2001, having a shortened statutory period for response set to expire on March 23, 2001, the Applicants elect claims 1-15 with traverse. The Commissioner is authorized to charge \$36.00 for two (2) additional claims to Deposit Account No. 20-0782/AMAT/3786/BTP, along with any other fees to make this response timely.

THE PENDING CLAIMS:

Please cancel claims 1-29:

1. (Cancelled) A method of planarizing a wafer surface containing:
an interlayer dielectric having an upper surface and a plurality of spaced apart openings;
a barrier layer lining the opening and on the upper surface of the interlayer dielectric;
and
copper (Cu) or a Cu alloy filling the openings and on the interlayer dielectric;
the method comprising the sequential steps of: